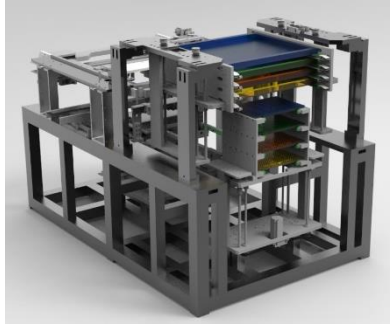
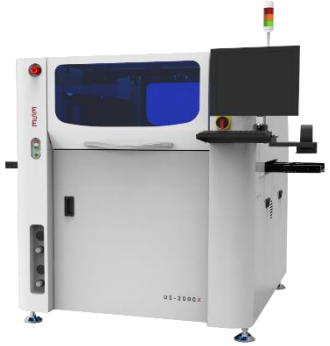
LIST OF 2019 INTER NEPCON JAPAN

US-2000XF10 → Automotive



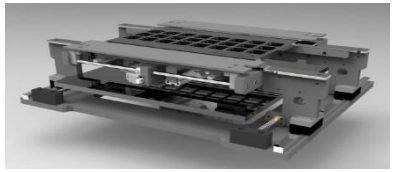
- Four or eight metal masks can be loaded on the back of the Printer.
- The XF10 supports Autobackup pins according to the metal mask specification.
- Depending on the metal mask specification of the model that was specified when the model was changed, it supports the use of the Back-up plate and the Back-up pin.
- As a result, the operator can easily change the model after the initial setting.
- Replaced metal masks can be removed and cleaned on the rear side during operation.

US-2000XH → SMART Mobile Phone



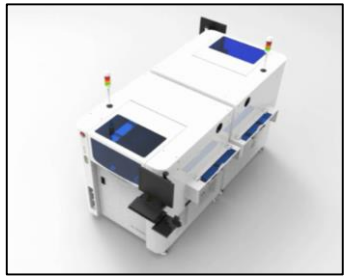
- 3.5 seconds core time.
- Printing time and cleaning time are out of core time.
- Enables cycle time of up to 10sec at 100mm/sec print time and 2.5sec cleaning time.
- To shorten a cycle time and to improve precision by an individual operating function by using a linear motor for a Y-axis a cleaner and Y-axis of a camera.
- Essentially, the XQ specification applies.

US-2000BP → Semiconductor



- Enables high-precision batch alignment of multi-array packages on the carrier.
- Enables batch printing after batch alignment.
- Improve productivity by printing multi-array packages in bulk.
- Printing alignment accuracy ±12.5 um @ 6 sigma

US-2000DX1 → Mobile, Semiconductor



- Dual-Lane maximizes productivity.
- The driving part and the electrical equipment part are in front of machine, and maintenance is easy.
- Cycle time is halved.
- The side conveyor is a Shuttle type, so there is no need for a out side conveyor.